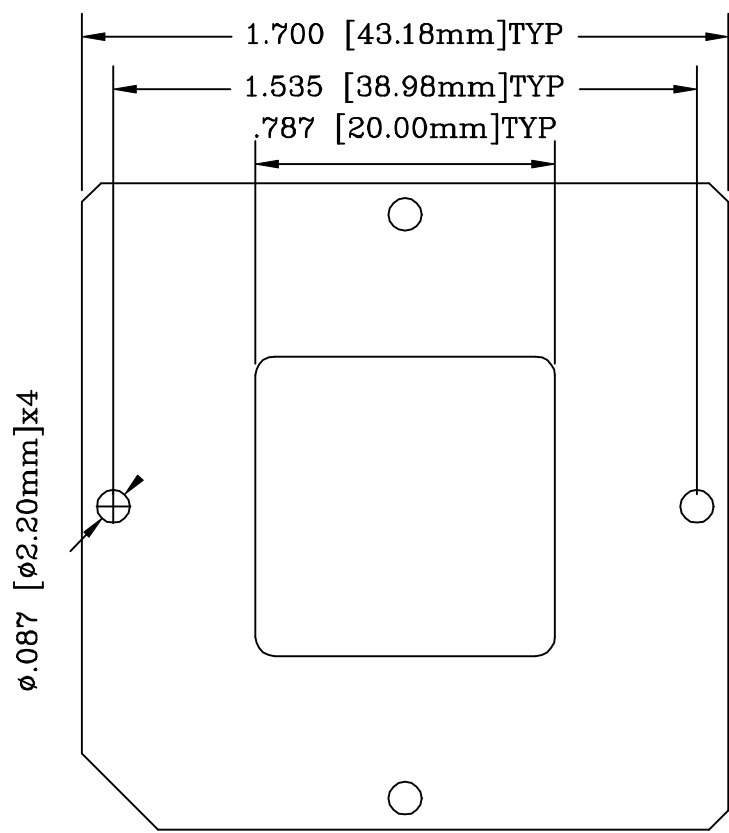


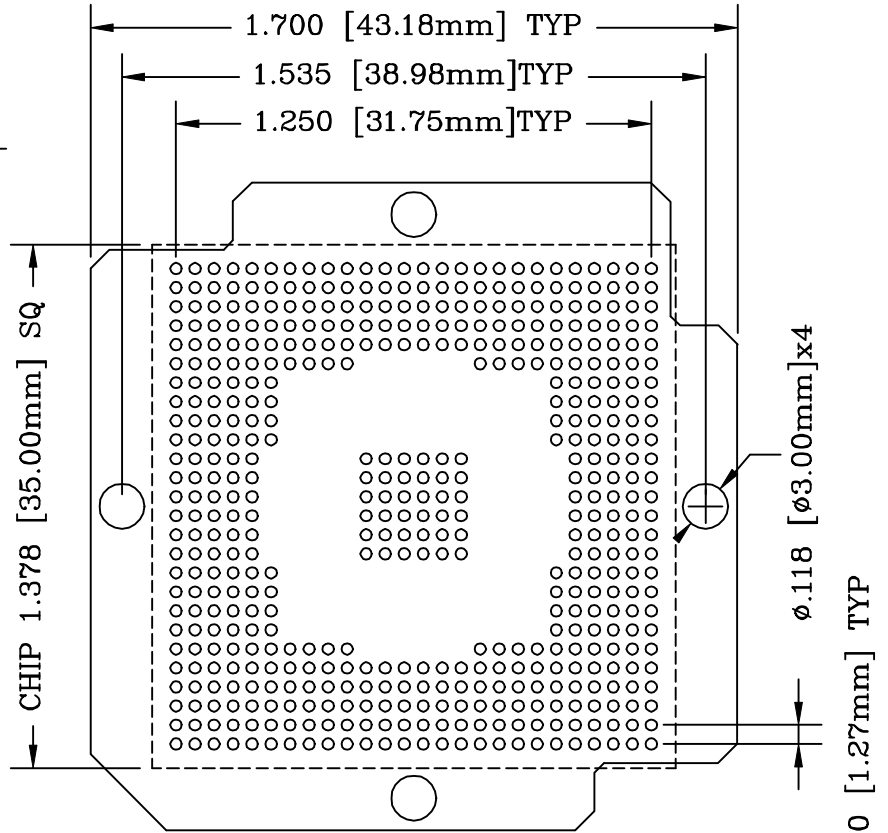
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	1/4/01	A.F.
B	UPDATED PAD LAYOUT AND DIMS	03/21/01	H.N.

SKT 1005  
DOD 41005



RETENTION FRAME

SCALE 2:1

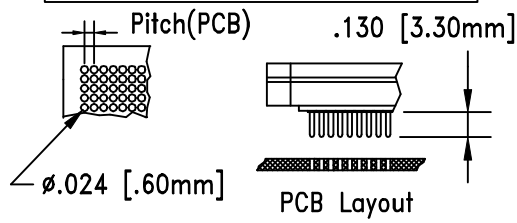
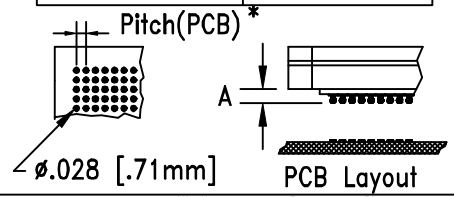


SOCKET

RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE	
REGULAR SMT STYLE	RAISED SMT STYLE
XX = (-SM)	XX = (-RC)
YY = (-30)	YY = (-29)

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET)
YY = (-70)



30= standard SMD ("A" = .047 [1.20mm])  
29= raised SMD ("A" = .197 [5.00mm])  
BALL DIAMETER FOR:  
-29(RC) = .026 [0.66mm]  
-30(SM) = .026 [0.66mm]

PIN DIAMETER FOR:  
-70(ET) = .018 [0.45mm]

\* The pitch dimension depends on your Ball Grid Array Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 492
LEAD PITCH	= 1.27mm
GRID SIZE	= 26X26
PACKAGE SIZE	= 35.00mm

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



**Emulation Technology, Inc.**  
— VLSI and SMT ADAPTERS and ACCESSORIES —

2344 Walsh Avenue, Bldg. F  
Santa Clara, Ca 95051

TEL:(408)982-0660  
FAX:(408)982-0664

SHEET: 1 OF 1  
DATE: 1/4/01  
REVISION:

ASSEMBLY DRAWING

CHECKED: Perry Munroe  
DRAWN: Aaron Fine

ITEM: S-BGA-26-492-XX

DO NOT SCALE DRAWING

DESCRIPTION: BPW-492-2BG026-YY